

# **PC354N Series**

# Mini-flat Package, AC Input Photocoupler



#### **■** Description

**PC354N Series** contains an IRED optically coupled to a phototransistor.

It is packaged in a 4-pin Mini-flat package. Input-output isolation voltage(rms) is 3.75kV. Collector-emitter voltage is 80V(\*) and CTR is 20% to 400% at input current of ±1mA.

#### **■** Features

- 1. 4-pin Mini-flat package
- 2. Double transfer mold package (Ideal for Flow Soldering)
- 3. AC input type
- 4. High collector-emitter voltage (V<sub>CEO</sub>: 80V<sup>(\*)</sup>)
- 5. High isolation voltage between input and output  $(V_{iso(rms)}: 3.75kV)$ 
  - (\*) Up to Date code "P9" (September 2002)  $V_{CEO}$ : 35V. From the production Date code "J5" (May 1997) to "P9" (September 2002), however the products were screened by  $BV_{CEO} \ge 70V$ .

#### ■ Agency approvals/Compliance

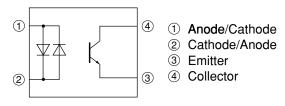
- 1. Recognized by UL1577 (Double protection isolation), file No. E64380 (as model No. **PC354**)
- 2. Package resin : UL flammability grade (94V-0)

#### ■ Applications

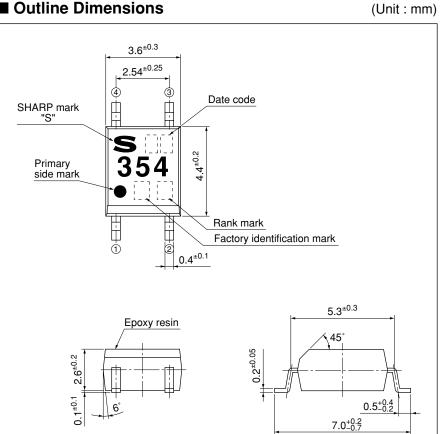
- 1. Hybrid substrates that require high density mounting.
- 2. Programmable controllers



## ■ Internal Connection Diagram



### **■** Outline Dimensions



Product mass: approx. 0.1g



# Date code (2 digit)

	1st o	digit		2nd digit	
	Year of p	roduction		Month of production	
A.D.	Mark	A.D	Mark	Month	Mark
1990	A	2002	P	January	1
1991	В	2003	R	February	2
1992	С	2004	S	March	3
1993	D	2005	T	April	4
1994	Е	2006	U	May	5
1995	F	2007	V	June	6
1996	Н	2008	W	July	7
1997	J	2009	X	August	8
1998	K	2010	A	September	9
1999	L	2011	В	October	0
2000	M	2012	С	November	N
2001	N	:	:	December	D

repeats in a 20 year cycle

# Factory identification mark

Factory identification Mark	Country of origin	
no mark	- Japan	
<b>4</b>	Indonesia	
$\overline{\mathcal{V}}$	Philippines	
_	China	

<sup>\*</sup> This factory marking is for identification purpose only. Please contact the local SHARP sales representative to see the actual status of the production.

Rank mark

Refer to the Model Line-up table



#### ■ Absolute Maximum Ratings

 $(T_{-}=25^{\circ}C)$ 

	$(1_a=23 C)$			
	Parameter	Symbol	Rating	Unit
	Forward current	$I_F$	±50	mA
Input	*1 Peak forward current	$I_{FM}$	±1	A
_	Power dissipation	P	70	mW
	Collector-emitter voltage	$V_{CEO}$	*4 80	V
Output	Emitter-collector voltage	$V_{ECO}$	6	V
Out	Collector current	$I_C$	50	mA
	Collector power dissipation	$P_{C}$	150	mW
-	Total power dissipation	P <sub>tot</sub>	170	mW
Operating temperature		$T_{opr}$	-30 to +100	°C
Storage temperature		$T_{stg}$	-40 to +125	°C
*2]	Isolation voltage	V <sub>iso (rms)</sub>	3.75	kV
*3 (	Soldering temperature	$T_{sol}$	260	°C

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# **■** Electro-optical Characteristics

 $(T_a=25^{\circ}C)$ 

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
Innut	Forward voltage		$V_{F}$	$I_F = \pm 20 \text{mA}$	-	1.2	1.4	V
Input	Terminal capacitance		$C_{t}$	V=0, f=1kHz	-	30	250	pF
	Collector dark current		$I_{CEO}$	$V_{CE}=50V, I_{F}=0$	_	_	100	nA
Output	Collector-emitter breakdown voltage		$BV_{CEO}$	$I_{C}=0.1 \text{ mA}, I_{F}=0$	*5 80	_	_	V
	Emitter-collector breakdown voltage		$BV_{ECO}$	$I_E=10\mu A, I_F=0$	6	-	-	V
	Collector current		$I_{C}$	$I_F=\pm 1$ mA, $V_{CE}=5$ V	0.2	_	4.0	mA
	Collector-emitter saturation voltage		V <sub>CE (sat)</sub>	$I_F=\pm 20mA$ , $I_C=1mA$	_	0.1	0.2	V
Transfer characteristics	Isolation resistance		$R_{ISO}$	DC500V, 40 to 60%RH	5×10 <sup>10</sup>	1×10 <sup>11</sup>	-	Ω
	Floating capacitance		$C_{\mathrm{f}}$	V=0, $f=1MHz$	-	0.6	1.0	pF
	Response time	Rise time	$t_r$	V 2V I 2 A D 1000	_	4	18	μs
		Fall time	$t_{\mathrm{f}}$	$V_{CE}$ =2V, $I_{C}$ =2mA, $R_{L}$ =100 $\Omega$	-	3	18	μs

<sup>\*5</sup> From the production Date code "J5" (May 1997) to "P9" (September 2002), however the products were screened by BV<sub>CEO</sub>≥70V.

<sup>\*1</sup> Pulse width≤100μs, Duty ratio : 0.001 \*2 40 to 60%RH, AC for 1 minute, f=60Hz

<sup>\*3</sup> For 10s

<sup>\*4</sup> Up to Date code "P9" (September 2002)  $V_{\text{CEO}}$  : 35V.



## **■** Model Line-up

Doolsooo	Тар	ing	- Rank mark	I <sub>C</sub> [mA]
Package	3 000 pcs/reel	750 pcs/reel		$(I_F=\pm 1 \text{mA}, V_{CE}=5 \text{V}, T_a=25 ^{\circ}\text{C})$
Madal Na	PC354N	PC354NT	A or no mark	0.2 to 4.0
Model No.	PC354N1	PC354N1T	A	0.5 to 1.5

Please contact a local SHARP sales representative to inquire about production status and Lead-Free options.



Fig.1 Forward Current vs. Ambient Temperature

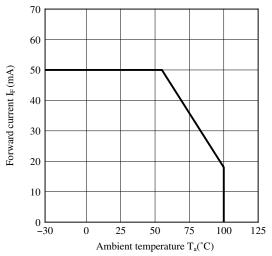


Fig.3 Collector Power Dissipation vs.
Ambient Temperature

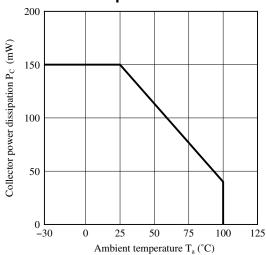


Fig.5 Peak Forward Current vs. Duty Ratio

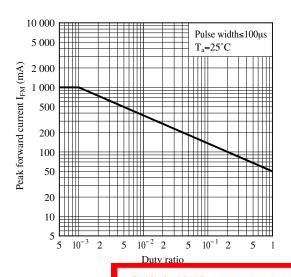


Fig.2 Diode Power Dissipation vs. Ambient Temperature

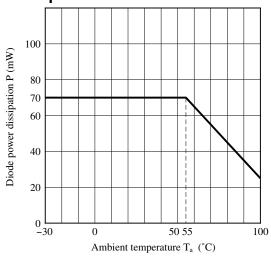


Fig.4 Total Power Dissipation vs. Ambient Temperature

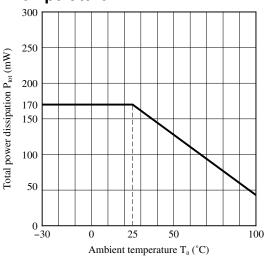


Fig.6 Forward Current vs. Forward Voltage

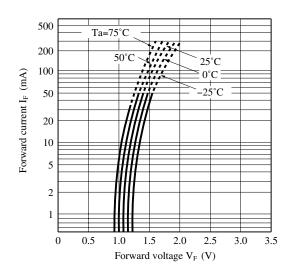




Fig.7 Current Transfer Ratio vs. Forward Current

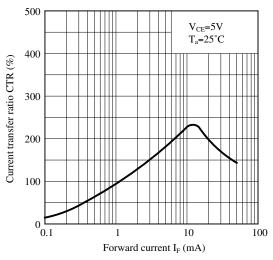


Fig.9 Relative Current Transfer Ratio vs. Ambient Temperature

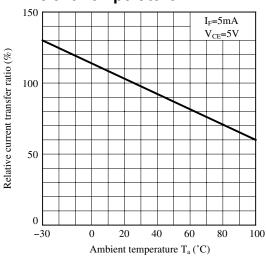


Fig.11 Collector Dark Current vs. Ambient Temperature

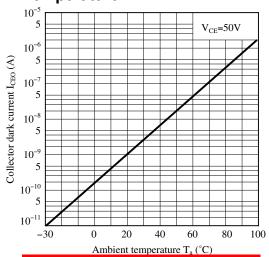


Fig.8 Collector Current vs. Collector-emitter Voltage

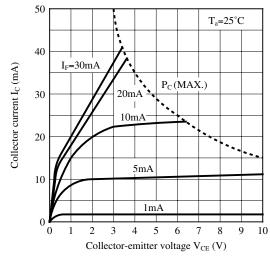


Fig.10 Collector - emitter Saturation Voltage vs. Ambient Temperature

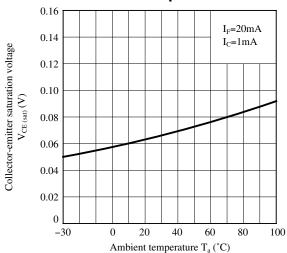


Fig.12 Response Time vs. Load Resistance

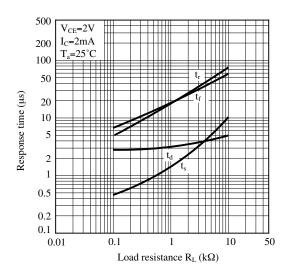
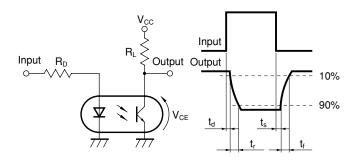


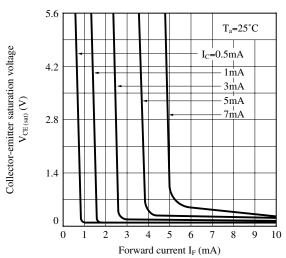


Fig.13 Test Circuit for Response Time



Please refer to the conditions in Fig.12

Fig.14 Collector-emitter Saturation Voltage vs. Forward Current



Remarks: Please be aware that all data in the graph are just for reference and not for guarantee.



#### **■** Design Considerations

## Design guide

While operating at I<sub>F</sub><1.0mA, CTR variation may increase.

Please make design considering this fact.

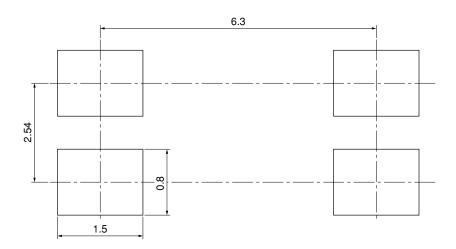
This product is not designed against irradiation and incorporates non-coherent IRED.

## Degradation

In general, the emission of the IRED used in photocouplers will degrade over time.

In the case of long term operation, please take the general IRED degradation (50% degradation over 5years) into the design consideration.

## Recommended Foot Print (reference)



(Unit:mm)

<sup>☆</sup> For additional design assistance, please review our corresponding Optoelectronic Application Notes.



#### ■ Manufacturing Guidelines

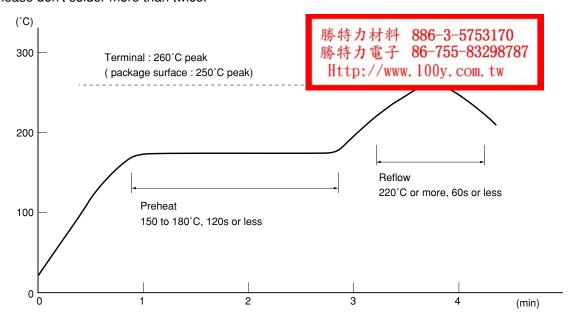
## Soldering Method

#### Reflow Soldering:

Reflow soldering should follow the temperature profile shown below.

Soldering should not exceed the curve of temperature profile and time.

Please don't solder more than twice.



#### Flow Soldering:

Due to SHARP's double transfer mold construction submersion in flow solder bath is allowed under the below listed guidelines.

Flow soldering should be completed below 260°C and within 10s.

Preheating is within the bounds of 100 to 150°C and 30 to 80s.

Please don't solder more than twice.

#### Hand soldering

Hand soldering should be completed within 3s when the point of solder iron is below 400°C.

Please don't solder more than twice.

#### Other notices

Please test the soldering method in actual condition and make sure the soldering works fine, since the impact on the junction between the device and PCB varies depending on the tooling and soldering conditions.



#### Cleaning instructions

#### Solvent cleaning:

Solvent temperature should be 45°C or below Immersion time should be 3minutes or less

#### Ultrasonic cleaning:

The impact on the device varies depending on the size of the cleaning bath, ultrasonic output, cleaning time, size of PCB and mounting method of the device.

Therefore, please make sure the device withstands the ultrasonic cleaning in actual conditions in advance of mass production.

#### Recommended solvent materials:

Ethyl alcohol, Methyl alcohol and Isopropyl alcohol

In case the other type of solvent materials are intended to be used, please make sure they work fine in actual using conditions since some materials may erode the packaging resin.

#### Presence of ODC

This product shall not contain the following materials.

And they are not used in the production process for this device.

Regulation substances: CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.

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# ■ Package specification

## ● Tape and Reel package

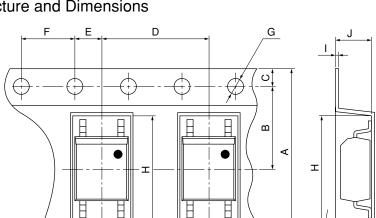
1. 3 000pcs/reel Package materials

Carrier tape: A-PET (with anti-static material)

Cover tape: PET (three layer system)

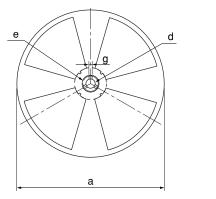
Reel: PS

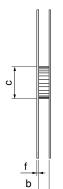
Carrier tape structure and Dimensions



**Dimensions List** (Unit: mm) A В C D Е F G  $12.0^{\pm0.3}$ 5.5<sup>±0.1</sup>  $1.75^{\pm0.1}$  $8.0^{\pm0.1}$  $2.0^{\pm0.1}$  $4.0^{\pm0.1}$  $\phi 1.5^{+0.1}_{-0.1}$ K Η I J 0.3±0.05 3.1±0.1  $7.4^{\pm0.1}$  $4.0^{\pm0.1}$ 

## Reel structure and Dimensions

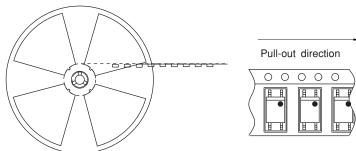




K

Dimensio	ns List	(Unit: mm)		
a	b	С	d	
370 13.5±1.5		80 <sup>±1.0</sup>	13 <sup>±0.5</sup>	
e	f	g		
21 <sup>±1.0</sup>	2.0±0.5	2.0 <sup>±0.5</sup>		

# Direction of product insertion



[Packing: 3 000pcs/reel]



## 2. 750pcs/reel

## Package materials

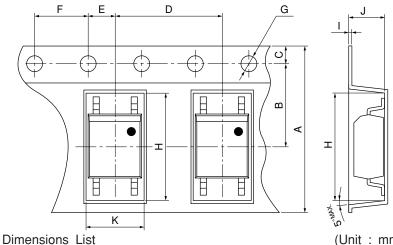
Carrier tape: A-PET (with anti-static material)

Cover tape: PET (three layer system)

Reel: PS

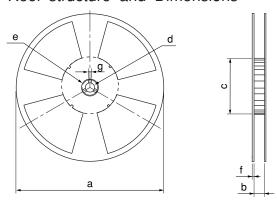
#### Carrier tape structure and Dimensions





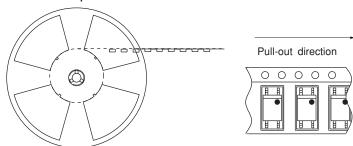
(Unit: mm) C D Е F G 5.5<sup>±0.1</sup> 12.0±0.3 1.75<sup>±0.1</sup>  $8.0^{\pm0.1}$ 2.0±0.1  $4.0^{\pm0.1}$  $\phi 1.5^{+0.1}_{-0}$ Н Ι K  $7.4^{\pm0.1}$  $0.3^{\pm0.05}$  $3.1^{\pm0.1}$  $4.0^{\pm0.1}$ 

#### Reel structure and Dimensions



Dimensio	ns List	(Unit: mm)			
a	b	c	d		
180	180 13.5±1.5		13 <sup>±0.5</sup>		
e	f	g			
21 <sup>±1.0</sup>	2.0±0.5	2.0±0.5			

## Direction of product insertion



[Packing: 750pcs/reel]



#### **■** Important Notices

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  - --- Industrial control
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  - --- Consumer electronics
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- --- Traffic signals
- --- Gas leakage sensor breakers
- --- Alarm equipment
- --- Various safety devices, etc.
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